



Material Content Data Sheet



Sales Product Name		TLE4270-2D		Issued		28. August 2013		
MA#		MA000723264						
Package		PG-TO252-5-11		Weight*		367.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.930	1.34	1.34	13426	13426
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		557	
	inorganic material	phosphorus	7723-14-0	0.061	0.02		167	
	non noble metal	copper	7440-50-8	204.243	55.62	55.70	556243	556967
wire	non noble metal	aluminium	7429-90-5	0.191	0.05	0.05	519	519
encapsulation	organic material	carbon black	1333-86-4	0.293	0.08		797	
	plastics	epoxy resin	-	13.467	3.67		36678	
	inorganic material	silicondioxide	60676-86-0	132.624	36.12	39.87	361194	398669
leadfinish	non noble metal	tin	7440-31-5	5.072	1.38	1.38	13815	13815
plating	non noble metal	nickel	7440-02-0	0.076	0.02		208	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	0	208
solder	noble metal	silver	7440-22-4	0.151	0.04		410	
	non noble metal	tin	7440-31-5	0.120	0.03		328	
	non noble metal	lead	7439-92-1	5.749	1.57	1.64	15658	16396
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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